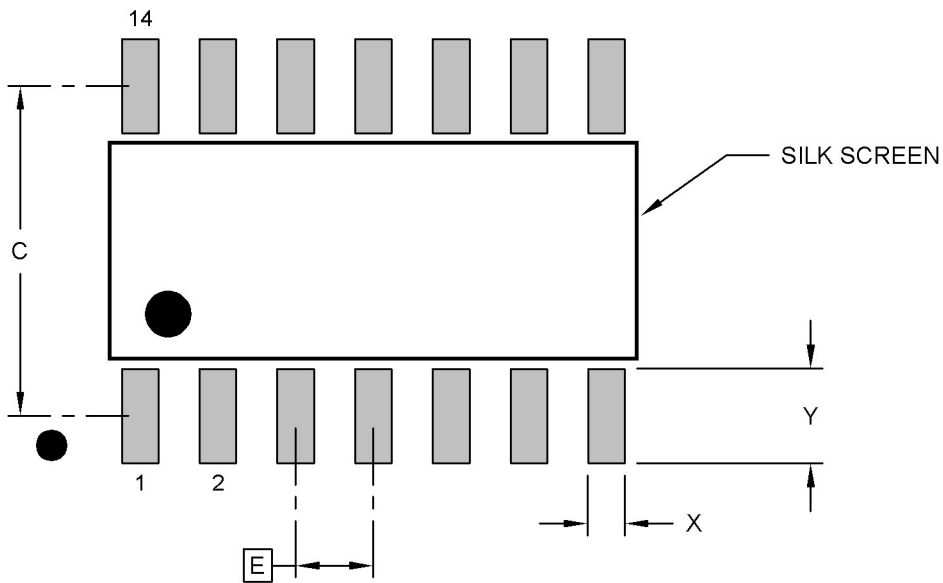


14-Lead Plastic Small Outline (D3X) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at <http://www.microchip.com/packaging>



RECOMMENDED LAND PATTERN

		Units	MILLIMETERS		
		Dimension Limits	MIN	NOM	MAX
Contact Pitch	E			1.27 BSC	
Contact Pad Spacing	C			5.40	
Contact Pad Width (X14)	X				0.60
Contact Pad Length (X14)	Y				1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.